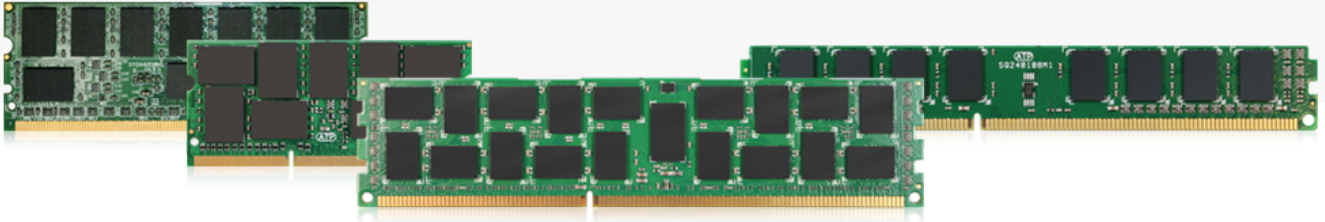




DDR3

The Global Leader in Specialized Storage and Memory Solutions



Key Features

- Density: 1 GB to 16 GB
- Chipkill support
- Fly-by command/address/control bus with on-DIMM termination
- Higher bandwidth performance, effectively up to 1866 MT/s
- Better performance at low power; 1.5V (Normal) and 1.35V (Low Voltage)

Operating at 1.5V (normal) and 1.35V (low voltage) and with a transfer speed of up to 1866 MT/s, ATP DDR3 modules deliver better performance while consuming significantly less power than DDR2 memory. ATP DDR3 modules are supported by the Intel® Core™ i7 Series, the AMD AM3 Phenom™ processor, and the latest AMD Embedded Enterprise Chipsets. DDR3 modules are not pin-compatible with the prior-generation modules and have alignment notches preventing them from being inserted into incompatible slots.

ATP offers DDR3 SDRAMs in a wide range of form factors and features including SO-DIMM and Mini-DIMM with low profile, very low profile (VLP) and ultra-low profile (ULP) options.

In addition to standard offerings, ATP's DDR3 product line has enhanced reliability options such as conformal coating for protection against dust, chemicals, extreme temperatures and corrosion. The 30μ" thickness of the gold finger plating ensures better durability and signal transmission quality.

Technologies & Add-On Services	30μ" Golden Finger	ATP TDBI	Wide Temperature	Anti-Sulfur Resistors	Conformal Coating	PCB Chamfer
RDIMM	●	●	▲	▲	—	▲
ECC UDIMM	●	●	▲	▲	▲	▲
Non-ECC UDIMM	●	●	▲	▲	▲	▲
ECC SO-DIMM	●	●	▲	▲	▲	▲
Non-ECC SO-DIMM	●	●	▲	▲	▲	▲
Mini-RDIMM	●	●	▲	▲	—	—
Mini-UDIMM	●	●	▲	▲	—	—

▲: Optional

Specifications

DDR3							
DIMM Type	RDIMM	ECC UDIMM	Non-ECC UDIMM	ECC SO-DIMM	Non-ECC SO-DIMM	Mini-RDIMM	Mini-UDIMM
Density	1 GB to 16 GB					1 GB to 8 GB	
Speed up to (MT/s)	1866					1600	
PCB Height*	Low profile / VLP / ULP	Low profile / VLP	Low profile / VLP	Low profile	Low profile / VLP / ULP		
Operating Temperature	0°C to 85°C / -40°C to 85°C						

* VLP: 0.74", ULP: below 0.74"

DDR3 8Gbit Component				
Form Factor	UDIMM	UDIMM ECC	SO-DIMM	SO-DIMM ECC
Density	16 GB			
Ranks	2			
Component Org	1G x 8			
Component Qty.	16	18	16	18
Speed up to (MT/s)	1600			
Technology	Mono			

Hot Items Ordering Information						
SPEED	SIZE	CHIP	HEIGHT	Ranks	P/N	
Unbuffered Non ECC Module DDR3-1600	4 GB	512x8	1.18"	1	AQ12P64A8BLK0M	
Unbuffered Non ECC Module DDR3-1600	8 GB	512x8	1.18"	2	AQ24P64B8BLK0M	
Unbuffered Non ECC SO-DIMM DDR3-1600	4 GB	512x8	1.18"	1	AW12P6438BLK0M	
Unbuffered Non ECC SO-DIMM DDR3-1600	8 GB	512x8	1.18"	2	AW24P64F8BLK0M	

Product spec and its related information are subject to change without advance notice.
Please refer to www.atpinc.com for latest information

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